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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/668,186	09/24/2003	Yutaka Takafuji	1248-0673P	4125
2292 7590 01/29/2008 BIRCH STEWART KOLASCH & BIRCH PO BOX 747 FALLS CHURCH, VA 22040-0747			EXAMINER SCHILLINGER, LAURA M	
			ART UNIT 2813	PAPER NUMBER
			NOTIFICATION DATE 01/29/2008	DELIVERY MODE ELECTRONIC

Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

Notice of the Office communication was sent electronically on above-indicated "Notification Date" to the following e-mail address(es):

mailroom@bskb.com

Office Action Summary

Application No.

10/668,186

Applicant(s)

TAKAFUJI ET AL.

Examiner

Laura M. Schillinger

Art Unit

2813

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) ☒ Responsive to communication(s) filed on 26 December 2007.
- 2a) ☒ This action is **FINAL**. 2b) ☐ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

- 4) ☒ Claim(s) 1-16 and 18-58 is/are pending in the application.
- 4a) Of the above claim(s) 1-15 and 39-57 is/are withdrawn from consideration.
- 5) ☒ Claim(s) 28 and 37 is/are allowed.
- 6) ☒ Claim(s) 16, 18-21, 23-27, 29, 36, 38 and 58 is/are rejected.
- 7) ☒ Claim(s) 22 is/are objected to.
- 8) ☐ Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on _____ is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

- 12) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☐ All b) ☐ Some * c) ☐ None of:
- ☐ Certified copies of the priority documents have been received.
 - ☐ Certified copies of the priority documents have been received in Application No. _____.
 - ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

- ☐ Notice of References Cited (PTO-892)
- ☐ Notice of Draftperson's Patent Drawing Review (PTO-948)
- ☒ Information Disclosure Statement(s) (PTO/SB/08)
Paper No(s)/Mail Date 12/26/07.
- ☐ Interview Summary (PTO-413)
Paper No(s)/Mail Date. _____
- ☐ Notice of Informal Patent Application
- ☐ Other: _____

DETAILED ACTION

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

Claims 16, 18-21, 23-24, 29-34, and 58 are rejected under 35 U.S.C. 102(b) as being anticipated by Yudasaka (JP 06-011729).

16. A semiconductor device, comprising:

a non-single-crystal silicon thin-film device manufactured from a non-single-crystal silicon thin film (303) and a single-crystal silicon thin-film device manufactured from a single-crystal silicon thin film (302), wherein the non-single-crystal silicon thin-film device and the single-crystal silicon thin-film device are provided in different areas of an insulating substrate (301) (Abs.see all- Representative Drawing 3) wherein the non-single crystal silicon thin film (303) and the single crystal silicon thin film (302) are each separated from the insulating substrate by a space or at least one other layer such that a surface of the non-single crystal silicon thin film that is nearest to the insulating substrate and a surface of the single crystal silicon thin film that is nearest to the insulating substrate are at different heights above the insulating substrate (Fig.3 and Fig.1-see Examiner's response to arguments below).

18. The semiconductor device as defined in claim 16, wherein, each of the non-single-crystal silicon thin-film device and the single-crystal silicon thin-film device either a MOS thin-film transistor or a MIS thin-film transistor (Abs- TFT is understood to be a MISFET).

19 . The semiconductor device as defined in claim 18, wherein, in the MOS thin-film transistor, a gate, a gate insulating film, and silicon are formed on the insulating substrate in this order (0020).

20. The semiconductor device as defined in claim 18, wherein, a thickness of a silicon thin film of the MOS thin-film transistor is about not more than 600 nm (0017).

21. The semiconductor device as defined in claim 18, wherein, a thickness of a single-crystal silicon thin film of the MOS thin-film transistor is about not more than 100 nm (0017) .

23. The semiconductor device as defined in claim wherein, the non-single-crystal silicon thin-film device is either a MOS non-single-crystal silicon thin-film transistor or a MIS non-single-crystal silicon thin-film transistor, and the single-crystal silicon thin-film device is a bipolar single-crystal silicon thin-film transistor (Fig.4).

24. The semiconductor device as defined in claim 17, wherein, the non-single-crystal silicon thin-film device is either a MOS non-single-crystal silicon thin-film transistor or a MIS non-single-crystal silicon thin-film transistor, and the single-crystal silicon thin-film device includes

at least either one of a MOS single-crystal silicon thin-film transistor and a bipolar single-crystal silicon thin-film transistor (Fig.4).

29. The semiconductor device as defined in claim 23, wherein, a thickness of the single-crystal silicon thin film of the bipolar single-crystal silicon thin-film transistor is about not more than 800 nm (0017).

30. The semiconductor device as defined in claim 16, wherein, the non-single-crystal polycrystalline silicon thin film or a continuous grain silicon thin film, and a MOS thin-film transistor manufactured from the non-single-crystal silicon thin film includes a non-single-crystal silicon, a gate insulating film, and a gate on the insulating substrate in this order (Fig.4).

31. The semiconductor device as defined in claim 16, wherein, the non-single-crystal silicon thin film is either one of a polycrystalline silicon thin film or a continuous grain silicon thin film, and a MOS thin-film transistor manufactured from the non-single-crystal silicon thin film includes a gate, a gate insulating film, and a non-single-crystal silicon on the insulating substrate in this order (0017-0021).

32. The semiconductor device as defined in claim 16, wherein, the non-single-crystal silicon thin film is an amorphous silicon thin film, and a MOS thin-film transistor or a MIS thin-film transistor, which is manufactured from the non-single-crystal silicon thin film, includes a gate, a gate insulating film, and a non-single-crystal silicon on the insulating substrate in this order (0017-0021).

33. The semiconductor device as defined in claim 16, silicon thin film is either a wherein, the non-single-crystal silicon . thin film is an amorphous silicon thin film, and a MOS thin-film transistor or a MIS thin-film transistor, which is manufactured from the non-single-crystal silicon thin film, includes a non-single-crystal silicon, a gate insulating film, and a gate on the insulating substrate in this order (0017-0021).

34. The semiconductor device as defined in claim 16, wherein, a difference of linear expansion between a single-crystal silicon constituting the single-crystal silicon thin-film device and the insulating substrate is about not more than 25Oppm, within a temperature range from a substantially room temperature to 600 (inherent property of the materials disclosed for a silicon single crystal layer and the insulated substrate).

58. The semiconductor device as defined in claim 16, wherein the single crystal thin film is bonded with the insulating thin-film device with the insulating substrate via an intervening inorganic insulating film (0013).

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

Claims 25-27 are rejected under 35 U.S.C. 103(a) as being unpatentable over Yudasaka as applied to claim 16 above, and further in view of Spitzer et al (WO/93/15589).

Yudasaka teaches forming a MOSFET however fails to teach the following claimed limitations.

Spitzer teaches the following claimed limitations as cited below:

25. The semiconductor device as defined in claim 17, wherein, the non-single-crystal silicon thin-film device is either a MOS non-single-crystal silicon thin-film transistor or a MIS non-single-crystal silicon thin-film transistor, and the single-crystal silicon thin-film device includes a MOS single-crystal silicon thin-film transistor, and an image sensor including a Schottky or PN-junction diode or a CCD image sensor (page 52, lines: 1-20).

26. The semiconductor device as defined in claim 24, wherein, a thickness of a single-crystal silicon thin-film of the MOS single-crystal silicon thin-film transistor is thinner than a thickness of a single-crystal silicon thin film of the bipolar single-crystal silicon thin-film transistor (page 28, lines: 1-5 and page 18, line: 25).

27. The semiconductor device as defined in claim 23, wherein, the bipolar single-crystal silicon thin-film transistor has such a structure that a base area, a collector area, and an emitter area are formed and provided in one plane (Fig.25B and page 52, lines: 1-20).

It would have been obvious to one of ordinary skill in the art at the time the invention was made to further include the circuitry as recited in claims 25-27 because such circuitry is considered to be conventional in the art of microdevices and the inclusion of additional circuitry is often necessary to form functional devices.

Claims 35-36 and 38 rejected under 35 U.S.C. 103(a) as being unpatentable over Yudasaka as applied to claim 16 above, and further in view of Okabe et al ('099).

Yudasaka teaches the limitations of claim 16 and a substrate made of various materials such as quartz- however fails to specify as recited by claims 35 and 36 wherein, the insulating substrate is a high strain point glass including an alkaline-earth alumino-borosilicate glass.

Okabe teaches forming a alkaline-earth alumino-borosilicate glass substrate and an alignment mark formed and detected through visible light (Col.16, lines: 65-68).

It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Yudasaka's teachings to further include a alkaline-earth alumino-borosilicate glass substrate and an alignment mark formed and detected through visible light as taught by Okabe because as Okabe teaches, such materials/methods are useful in MOS and BJT applications (Col.6, lines: 65-68).

Allowable Subject Matter

Claim 22 is objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.

The following is a statement of reasons for the indication of allowable subject matter:

In reference to claim 22, prior art fails to teach nor suggest the combination of the limitations of claim 18, wherein, a metal pattern of the MOS single-crystal silicon thin-film transistor is formed under a wiring rule which is more relaxed than a wiring rule of a gate pattern of the MOS single-crystal silicon thin-film transistor.

Claims 28 and 37 are allowed.

Response to Arguments

Applicant's arguments filed 10/29/07 have been fully considered but they are not persuasive. Applicant argues that Yudasaka fails to teach the newly added limitations of claim 16- however such an argument is not persuasive. Yudasaka teaches that the layers 302 and 303 are separated from the substrate by a space- the layers rest on top of the substrate and therefore do not occupy the same space as the substrate and may be interpreted as separated by a space. Secondly, as shown in Fig.1- the SOS structure consists of layers 101 and 102- see the description in the English translation para 0012 and 0013; layers 202 and 302 are deposited on the SOS substrate and therefore are separated from substrate layer 101 by layer 102. Lastly, it is noted that para 0001 teaches that the layers may be formed on an SOI substrate which would inherently have an insulating layer formed between the substrate and silicon layer. Applicant argues that claim 21 is not taught by Yudasaka because Yudasaka teaches that the single crystal layer is 5000A - this is incorrect- Yudasaka teaches that the single crystal layer is a 1000 A- see para 0016- and that the layers 202 and 203 in combination are 5000 A- see para 0016. Lastly, Applicant argues that there is no intervening inorganic insulating layer- this argument is not persuasive since para 0001 teaches that the layers may be formed wither on an SOI or SOS substrate- which inherently has an intervening insulating layer within the substrate.

Conclusion

THIS ACTION IS MADE FINAL. Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire **THREE MONTHS** from the mailing date of this action. In the event a first reply is filed within **TWO MONTHS** of the mailing date of this final action and the advisory action is not mailed until after the end of the **THREE-MONTH** shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than **SIX MONTHS** from the mailing date of this final action.

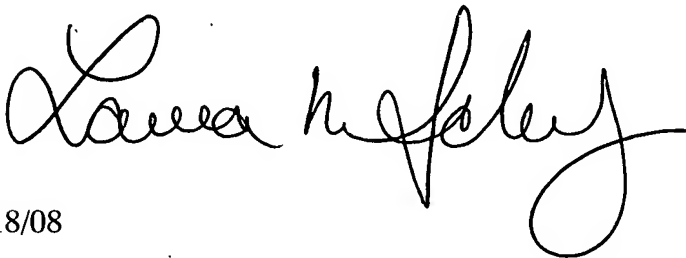
Any inquiry concerning this communication or earlier communications from the examiner should be directed to Laura M. Schillinger whose telephone number is (571) 272-1697. The examiner can normally be reached on M-T, R-F 7:00-5:00.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Carl W. Whitehead, Jr. can be reached on (571) 272-1702. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

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A handwritten signature in black ink, appearing to read "Laura M Schillinger", with a large, stylized flourish at the end.

Laura M Schillinger
Primary Examiner
Art Unit 2813

1/18/08